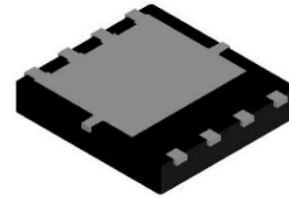


# WNM4014

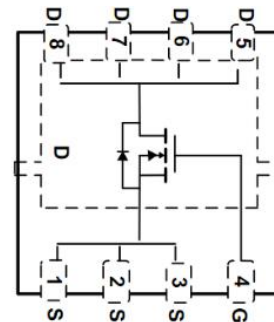
## Single N-Channel, 100V, 48A, Power MOSFET

[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

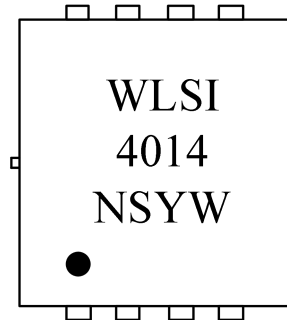
V <sub>DS</sub> (V)	Typical R <sub>DS(on)</sub> (mΩ)
100	5.6@ V <sub>GS</sub> =10V
	7.0@ V <sub>GS</sub> =4.5V



PDFN5X6-8L



Pin configuration (Top view)



4014 = Device Code  
 NS = Special Code  
 Y = Year  
 W = Week(A~Z)

**Marking**

### Description

The WNM4014 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM4014 is Pb-free.

### Features

- Trench Technology
- Supper high density cell design
- Low ON resistance
- Package PDFN5X6-8L

### Applications

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

### Order information

Device	Package	Shipping
WNM4014-8/TR	PDFN5X6-8L	3000/Tape&Reel

### Absolute Maximum ratings

Parameter	Symbol	Maximum	Unit	
Drain-Source Voltage	$V_{DS}$	100	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current <sup>d</sup>	$I_D$	$T_C=25^\circ\text{C}$	48	A
		$T_C=100^\circ\text{C}$	43	A
Pulsed Drain Current <sup>c</sup>	$I_{DM}$	185	A	
Continuous Drain Current	$I_{DSM}$	$T_A=25^\circ\text{C}$	21	A
		$T_A=70^\circ\text{C}$	17	
Avalanche Energy $L=0.3\text{mH}$	$E_{AS}$	118	mJ	
Power Dissipation <sup>b</sup>	$P_D$	$T_C=25^\circ\text{C}$	63	W
		$T_C=100^\circ\text{C}$	25	
Power Dissipation <sup>a</sup>	$P_{DSM}$	$T_A=25^\circ\text{C}$	6.0	W
		$T_A=70^\circ\text{C}$	3.8	
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ\text{C}$	
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ\text{C}$	

### Thermal resistance ratings

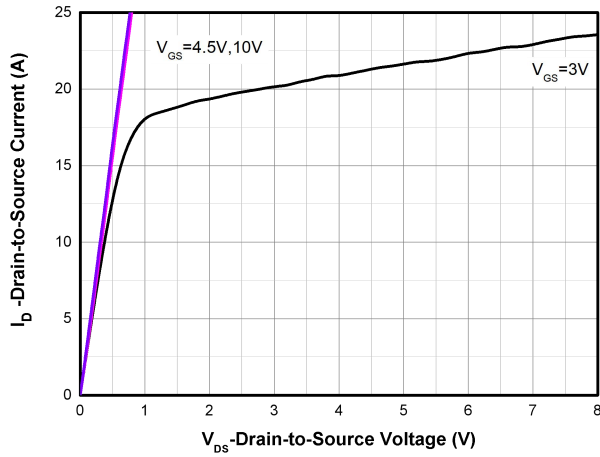
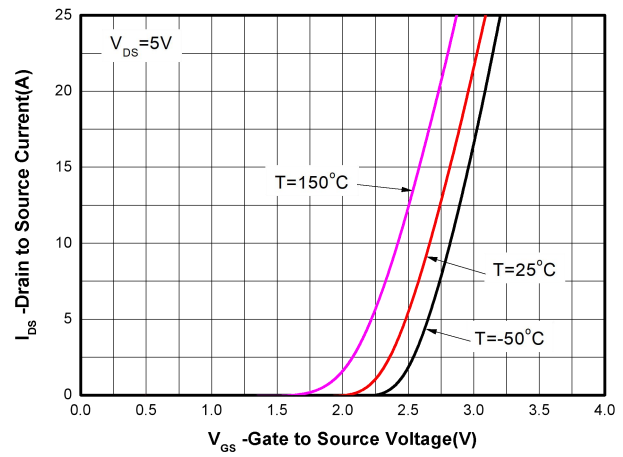
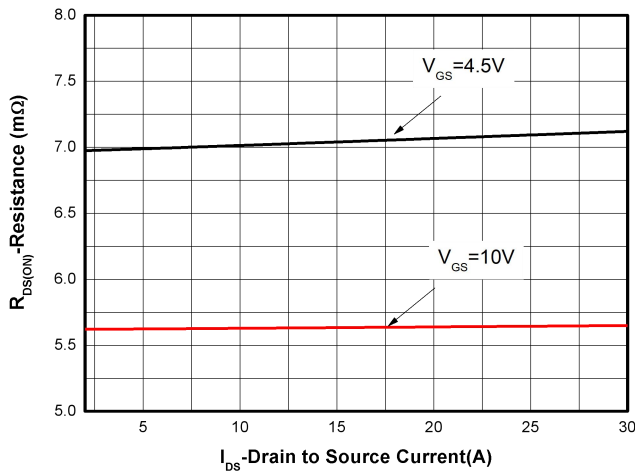
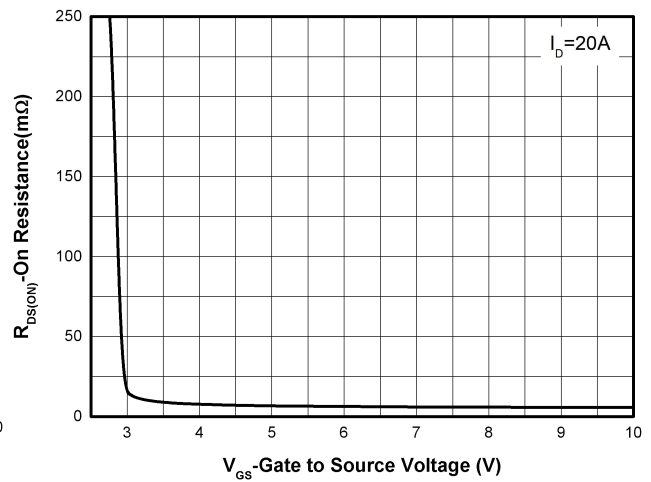
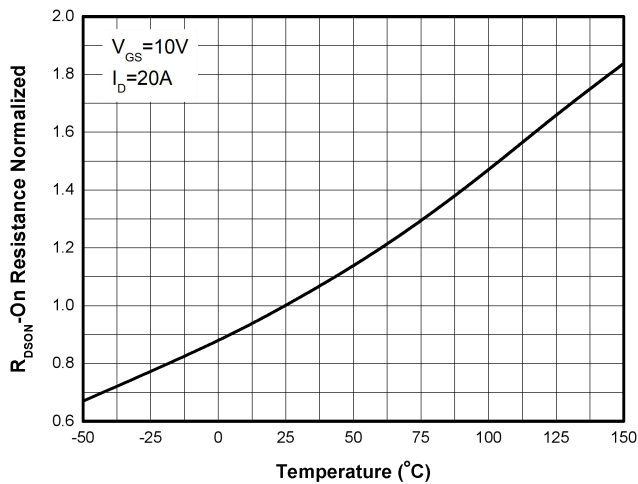
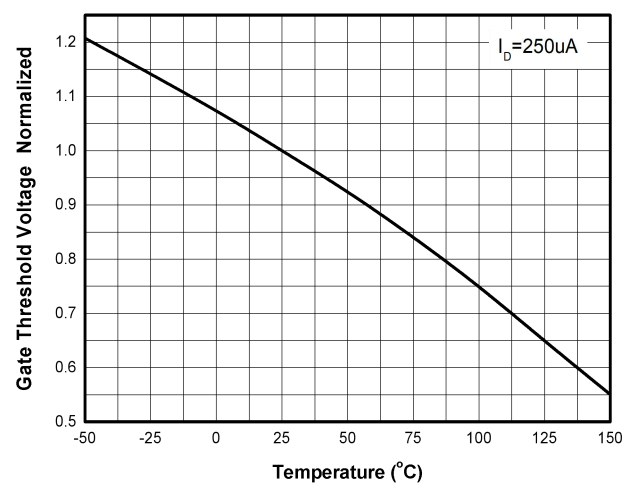
Single Operation					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$R_{\theta JA}$	$t \leq 10\text{ s}$	16	21	$^\circ\text{C/W}$
		Steady State	42	53	
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	1.6	2		

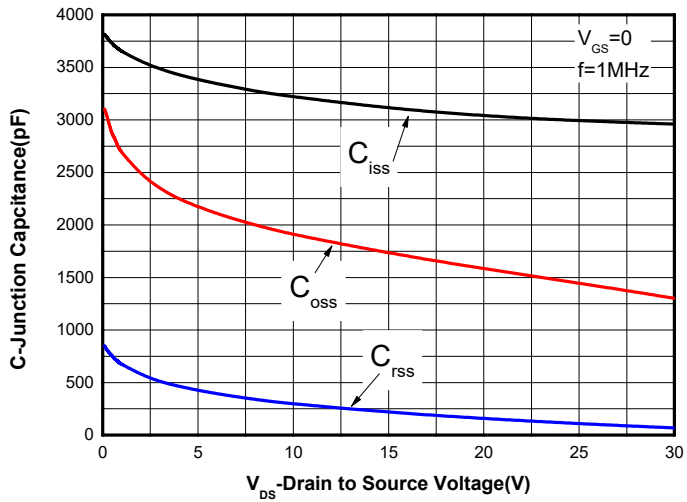
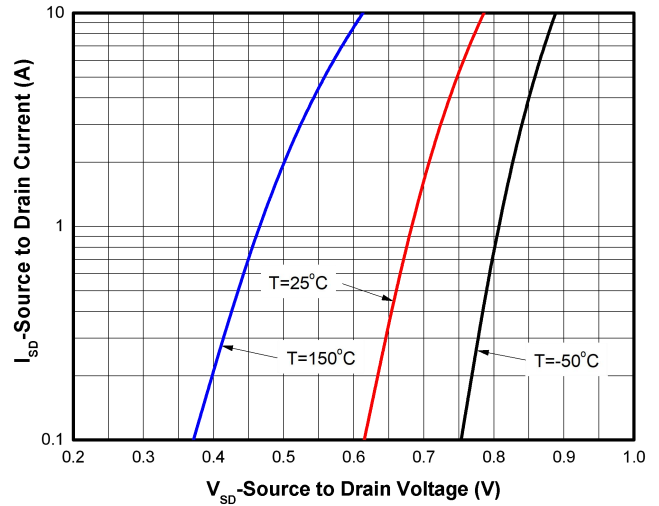
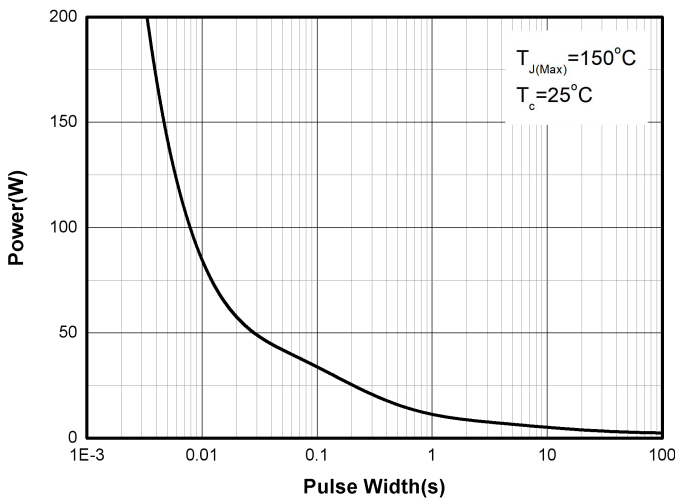
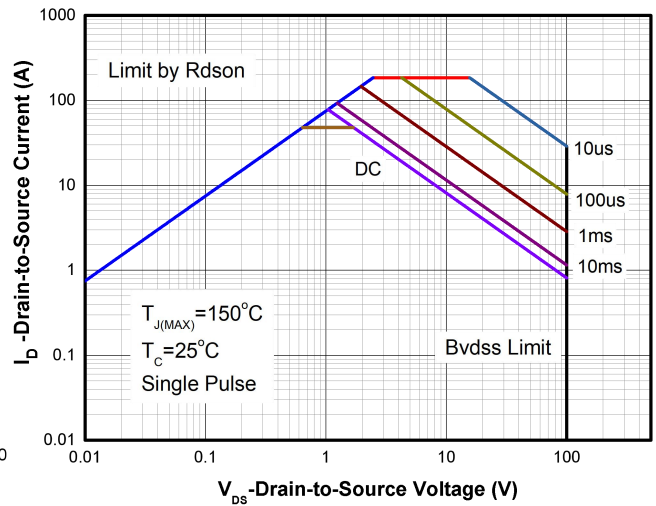
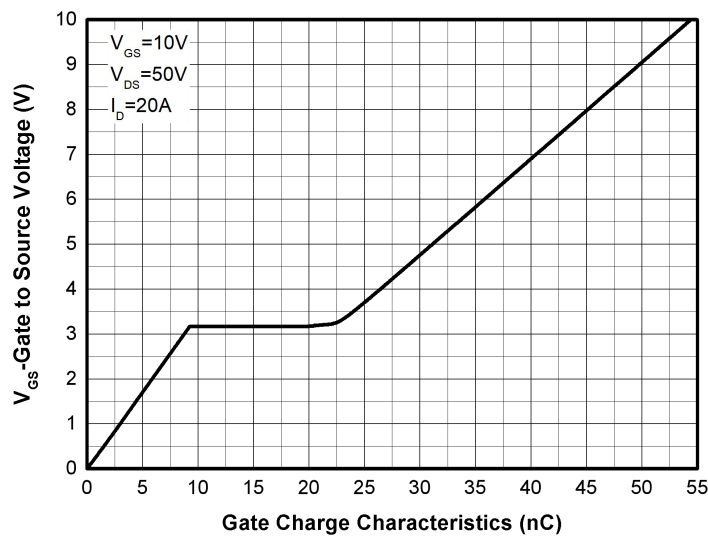
**Note:**

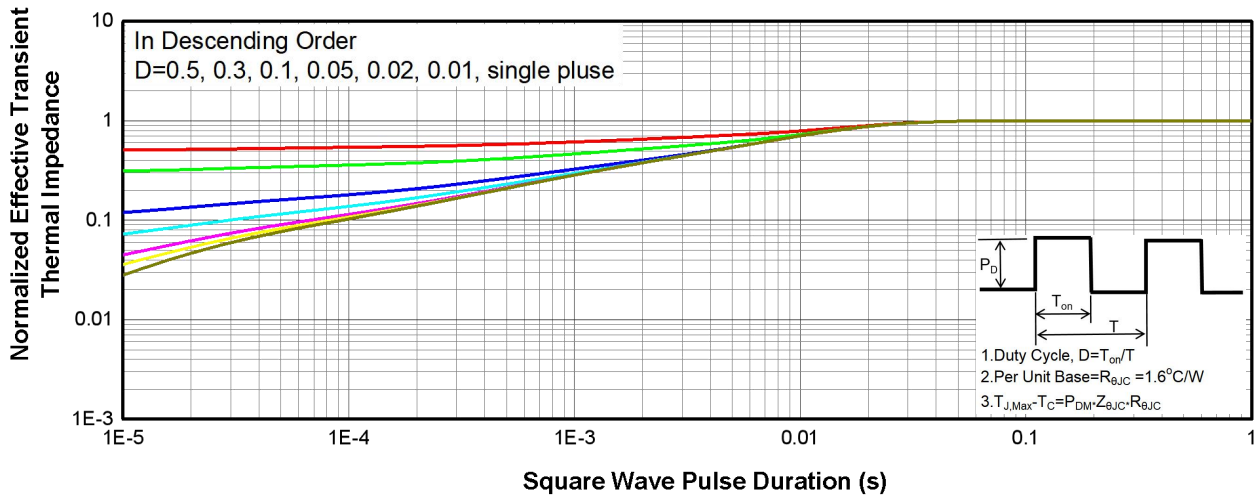
- a The value of  $R_{\theta JA}$  is measured with the device mounted on 1-inch<sup>2</sup> (6.45cm<sup>2</sup>) with 2oz.(0.071mm thick) Copper pad on a 1.5\*1.5 inch<sup>2</sup>, 0.06-inch thick FR4 PCB, in a still air environment with  $T_A = 25^\circ\text{C}$ . The power dissipation  $P_{DSM}$  is based on  $R_{\theta JA}$   $t \leq 10\text{s}$  value and the  $T_{J(MAX)}=150^\circ\text{C}$ . The value in any given application is determined by the user's specific board design.
- b The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- c Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial  $T_J = 25^\circ\text{C}$ , the maximum allowed junction temperature of 150 $^\circ\text{C}$ .
- d The maximum current rating by source bonding technology.
- e The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

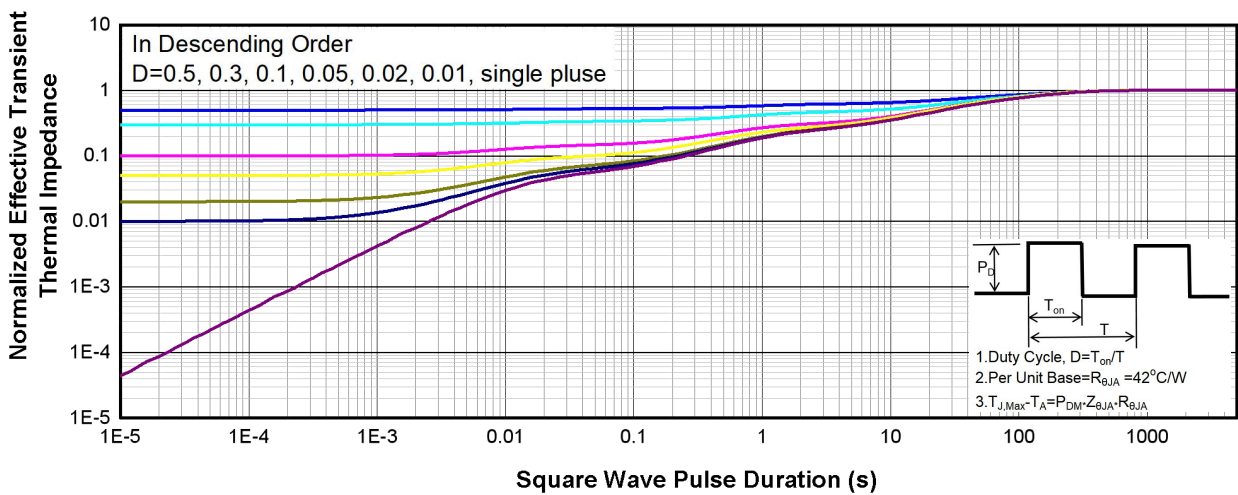
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.2	1.7	2.5	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		5.6	7.0	m $\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 15\text{A}$		7.0	10.0	
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{V}, f = 1.0\text{MHz},$ $V_{DS} = 30\text{ V}$		2960		pF
Output Capacitance	$C_{OSS}$			1303		
Reverse Transfer Capacitance	$C_{RSS}$			67		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10\text{ V}, V_{DS} = 50\text{V},$ $I_D = 20\text{A}$		55		nC
Threshold Gate Charge	$Q_{G(TH)}$			5.0		
Gate-to-Source Charge	$Q_{GS}$			9.3		
Gate-to-Drain Charge	$Q_{GD}$			13.2		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = 10\text{ V}, V_{DS} = 50\text{ V},$ $R_L = 2.5\ \Omega, R_G = 3\ \Omega$		38		ns
Rise Time	$t_r$			24		
Turn-Off Delay Time	$t_d(OFF)$			95		
Fall Time	$t_f$			15		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = 1\text{A}$		0.8	1.2	V

**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output Characteristics**

**Transfer Characteristics**

**On-Resistance vs. Drain Current**

**On-Resistance vs. Gate-to-Source Voltage**

**On-Resistance vs. Junction Temperature**

**Threshold Voltage vs. Temperature**

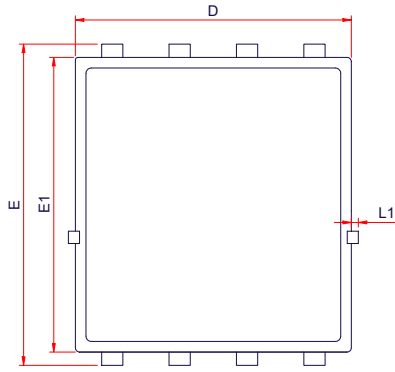

**Capacitance**

**Body Diode Forward Voltage**

**Single Pulse power**

**Safe Operating Power**

**Gate Charge Characteristics**



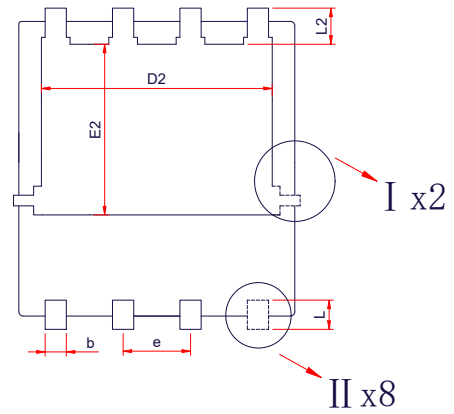
**Transient Thermal Response (Junction-to-Case)**



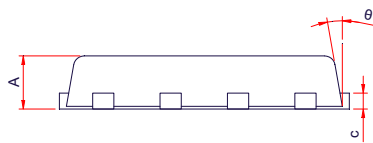
**Transient Thermal Response (Junction-to-Ambient)**

**PACKAGE OUTLINE DIMENSIONS**
**PDFN5X6-8L**


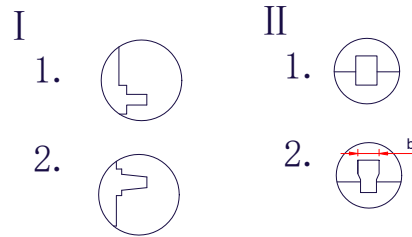
TOP VIEW



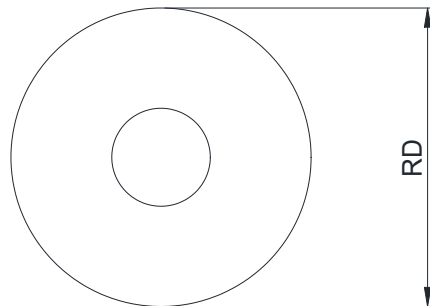
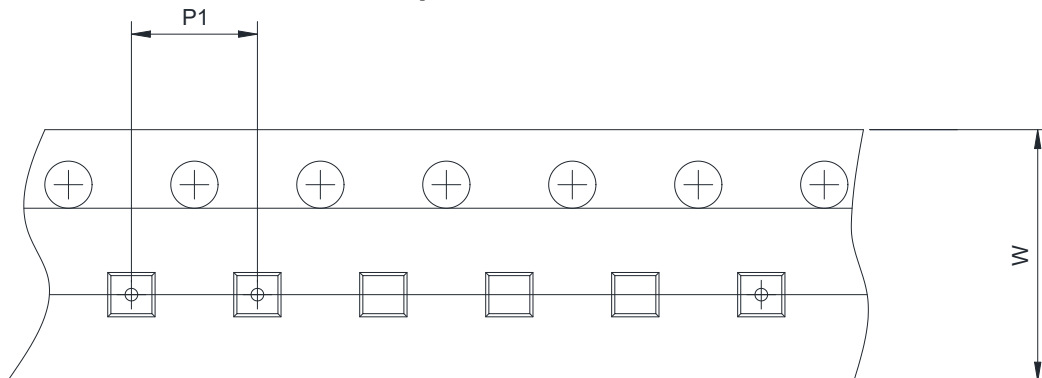
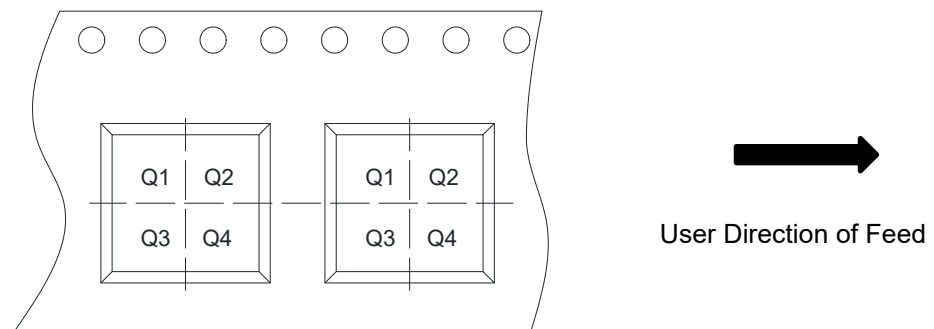
BOTTOM VIEW



SIDE VIEW



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.85	0.95	1.00
c	0.15	-	0.34
D	4.80	-	5.30
D2	3.82	-	4.45
E	5.90	-	6.15
E1	5.45	-	5.80
E2	3.18	3.45	3.73
e	1.27BSC		
b	0.30	0.40	0.50
L	0.45	-	0.71
L1	0.00	-	0.15
L2	0.68Ref		
$\theta$	0°	-	12°

**TAPE AND REEL INFORMATION**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


RD	Reel Dimension	<input type="checkbox"/> 7inch	<input checked="" type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input type="checkbox"/> 8mm	<input checked="" type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm	<input type="checkbox"/> 4mm <input checked="" type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1	<input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4



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[MCQ7328-TP](#) [SSM3J143TU,LXHF](#) [DMN12M3UCA6-7](#) [PJMF280N65E1\\_T0\\_00201](#) [PJMF380N65E1\\_T0\\_00201](#)  
[PJMF280N60E1\\_T0\\_00201](#) [PJMF600N65E1\\_T0\\_00201](#) [PJMF900N65E1\\_T0\\_00201](#)